Pack4EU

BOOST SEMICONDUCTOR PACKAGING IN EUROPE

Chips JU
Funded by the European Union
The project is supported by the CHIPS-JU and its members

There will be no Chips Act without Packaging

"Today, none of the most advanced logic and memory chips are manufactured at commercial scale in the United States. Bolstering frontend fabrication capacity without investing in packaging will limit supply-chain resiliency."
Source: 2023 NIST report –CHIPS for America

Apple chips made in the US still require assembly in Taiwan, report suggests

The Information says TSMC can only package advanced chips in Taiwan.

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Contributing Reporter
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Apple chief Tim Cook previously announced that the tech giant will be purchasing chips for its iPhones, Macs and other key products made in Taiwan Semiconductor Manufacturing Company's (TSMC) new factory in Phoenix, Arizona. It seemed like a huge win for the Biden administration, which signs the CHIPS Act into law last year to boost manufacturing in the US and lessen its reliance on overseas suppliers. Now, *The Information* has reported that even though the components for Apple's chips will be manufactured in the US, they'll still have to be sent back to TSMC's home country for assembly.

Our mission Federate the European Packaging Industry with a common leading edge technology roadmap for a European Leadership in Semiconductor

Supply chain resilience

Sovereignty

Green transition

Pack4EU at a Glance

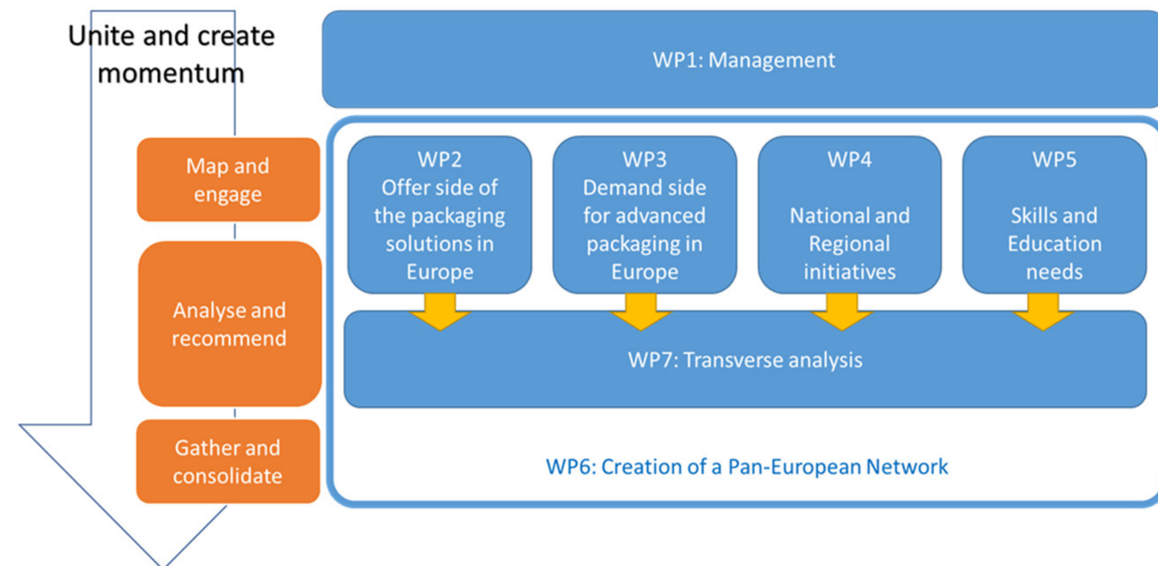
KDT-JU (Horizon Europe) -Call 2023-3-CSA (Coordination and Support Action)-
Topic 2 "Pan European network for Advanced Packaging made in Europe"

Pack4EU = Packaging, Assembly and Test for Europe

- **Duration:** 12 months, started July 2023
- **Budget:** 1M euros
- **7 Beneficiaries** (FR, NL, DE): **Blumorpho (coordinator)**, EPoSS (VDI-VDE: Pan EU Network), IMAPS FR (representing all IMAPS in EU), HT NL Silicon EU (representing all Clusters in EU), Semi EU, CEA SBEM (representing all RTO's marketing), TU Delft (for HR policies).

Actions

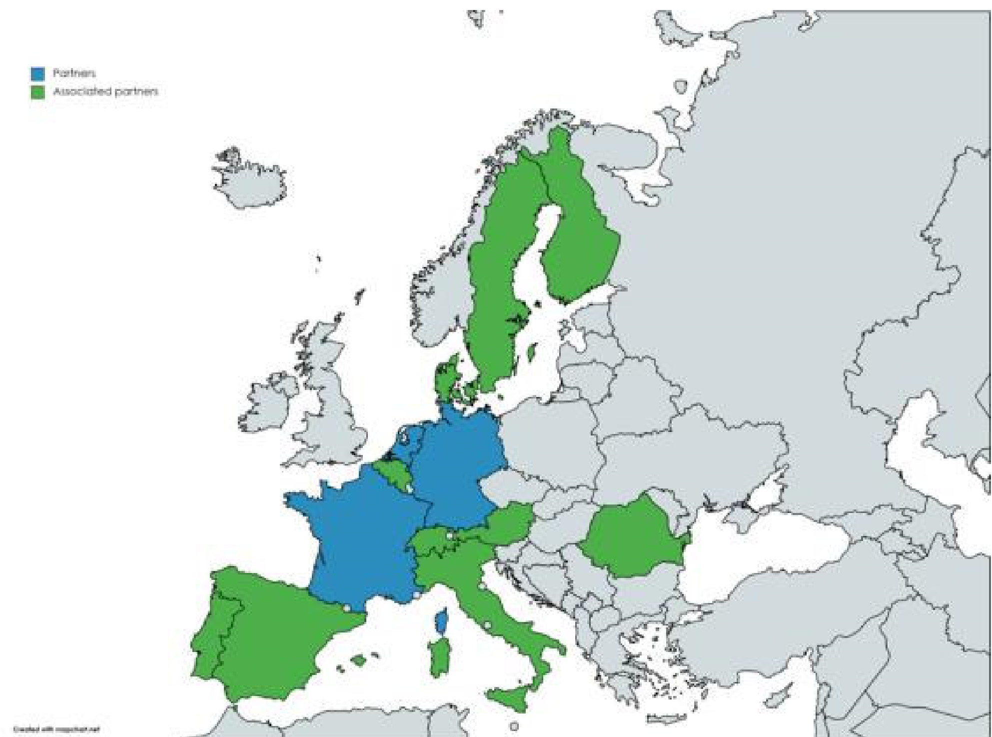
- **A major Packaging event.**
- Participation in all "Packaging" event in the next 12 months
- Recommendations to the EU commission



Our task = help and guide the European Commission on how to finance the EU packaging industry

Pack4EU at a Glance

43 Associated partners stakeholders along the complete semiconductor **Packaging value chain** (in 13 countries)



PACK4EU's approach

The **Pack4EU project's ambition is to help and guide the European Commission on how to finance the EU packaging industry**, by:

- **Federating the European Packaging industry and research institutions** by building a common roadmap and common goal towards competitiveness.
- **Involving the demand and the supply side**, the research community and the education will create a common understanding of the situation and define the direction to take to ensure that Europe gathers the technologies and talents to gain market share and maintains its sovereignty.

First results: PACK4EU's definition of Advanced Semiconductor Packaging for Europe

Advanced Semiconductor Packaging designates any novel set or combination of technology bricks, design or manufacturing processes aiming at assembling, packaging and testing semiconductor-based integrated circuits and components.

Advanced packaging serves the objectives of:

- Higher and heterogeneous integration
- Higher performance (any of electrical, mechanical, thermal, optical, quality, reliability, security)
- Higher cost efficiency by design and manufacturability
- More sustainable product life cycle
- Novel functionalities or emerging applications

Creating the Pan-European network

Network mapping and **identification of key players** and already **existing networks**
Understanding **needs, expectations, and challenges** of stakeholder (workshops, focus groups etc. dialogue)
Establishing a **network design** and **implementation plan**
Ensuring that the network is **visible** and has a wide reach and delivers value

Expansion

Stakeholder Engagement ...

Events

sencio functional packaging center, AEMtec, CSIC, AT&S, TELEDYNE e2V Everywhereyoulook, PacTech, ATOTECH, SAL SILICON AUSTRIA LABS, Fraunhofer ENAS, ALTER TECHNOLOGY, BOSCH, AEMtec, Amkor Technology, RoodMicrotec, infineon, imec, INL, NXP, PEERGROUP Integrating Automation & Information, THALES, adence, EGIDE, GlobalFoundries, CITC, MZ TECHNOLOGIES, xfab, intel, SERMA HCM.SYSTREL, Besi, life.augmented, muRata INNOVATOR IN ELECTRONICS, ATLANT 3D NANOSYSTEMS, MST Micro Systems Technologies, PRESTO Engineering, Critical manufacturing, Fraunhofer IZM, VTT, ERS

iMAPS, semi, High Tech NL, EPoSS European Association on Smart Systems Integration

Aknowledgement

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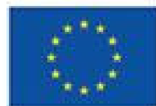

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Let's get acquainted...

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